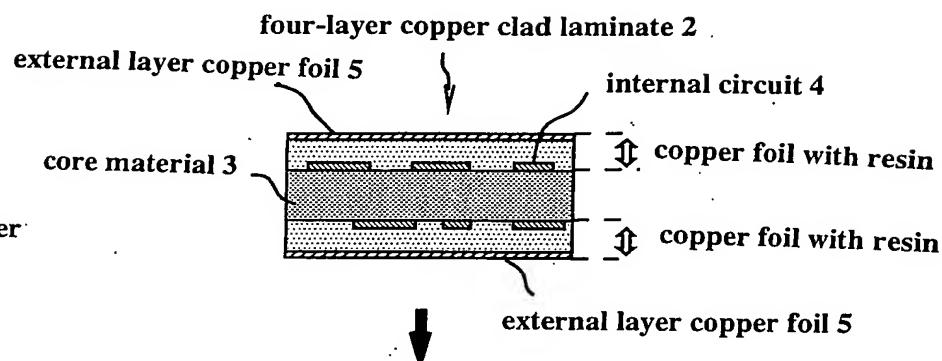


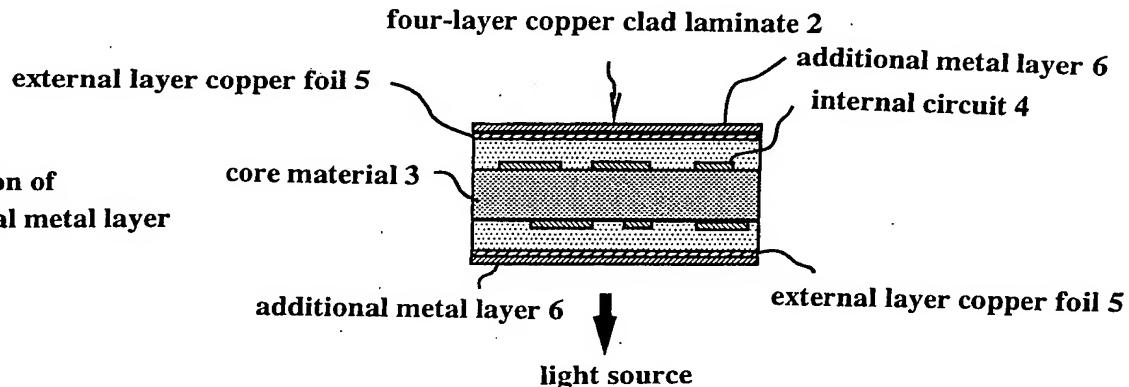
FIG. 1



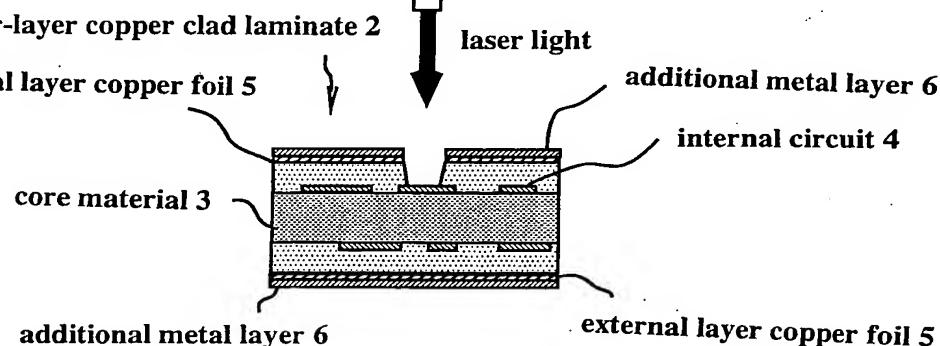
(a) Manufacture of four-layer copper clad laminate



(b) Formation of additional metal layer



(c) Hole-drilling by laser



(d) Peeling-off of an additional metal layer

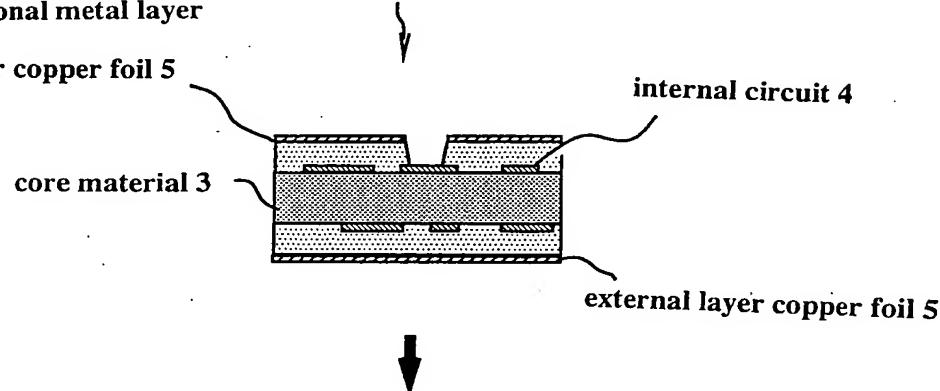


FIG. 2

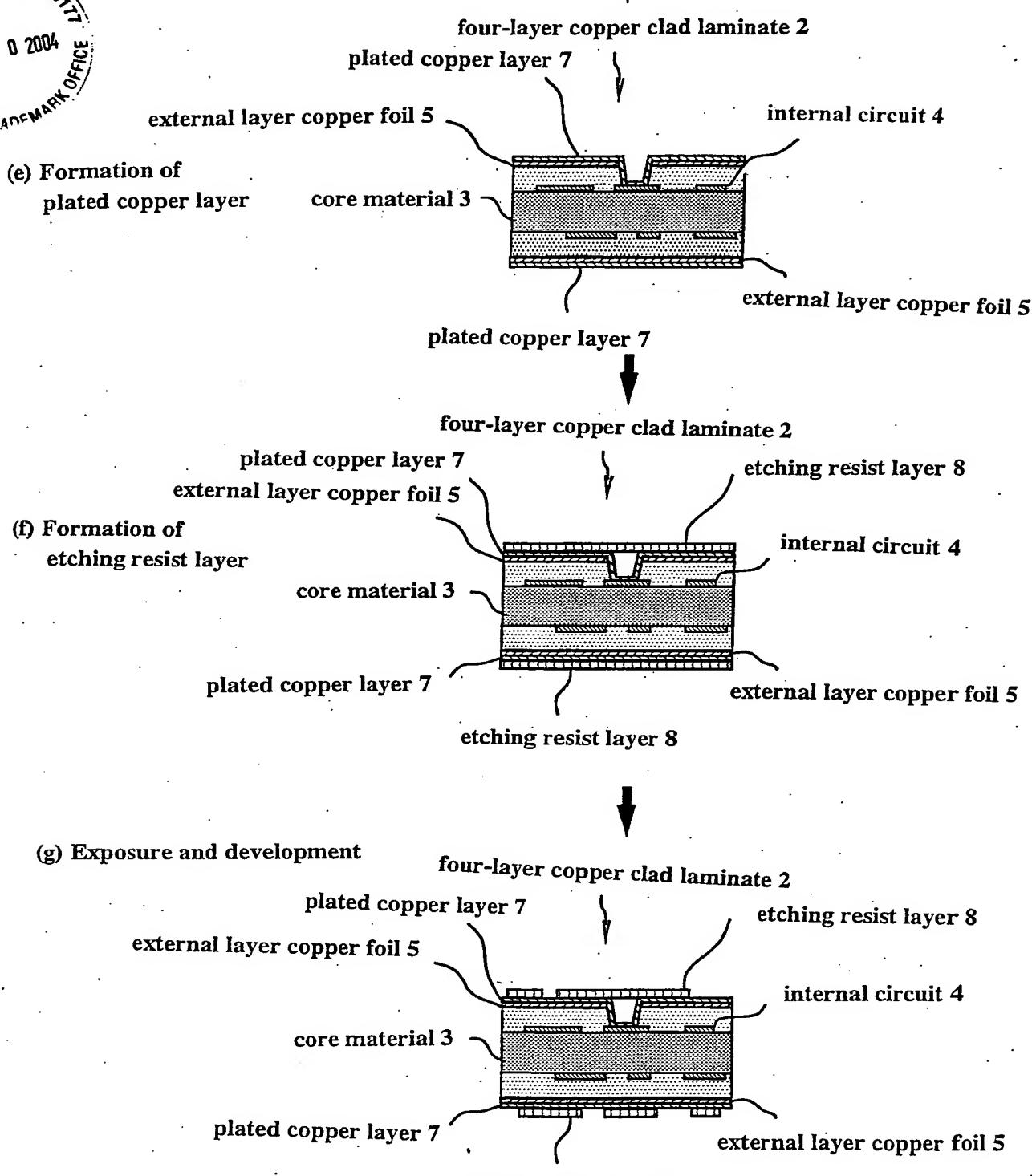
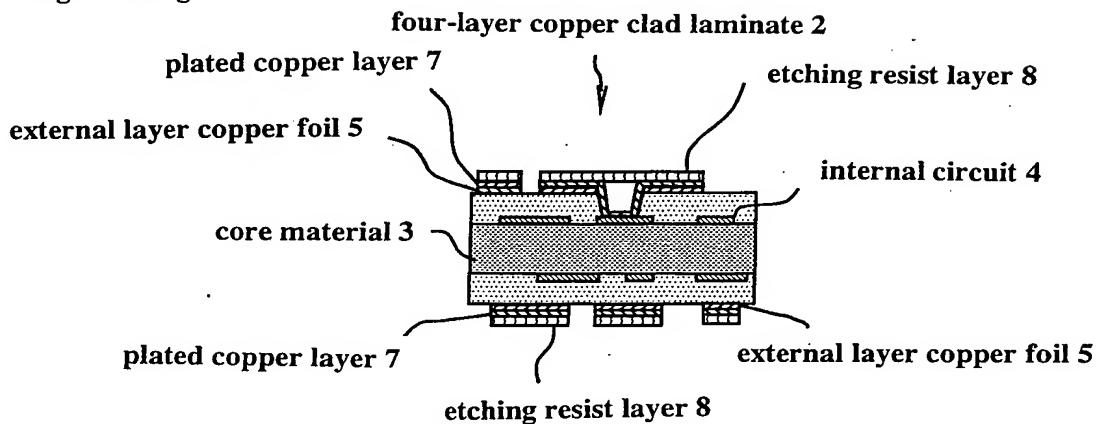


FIG. 3



(h) Formation of a circuit through etching



(i) Peeling-off of etching resist layer

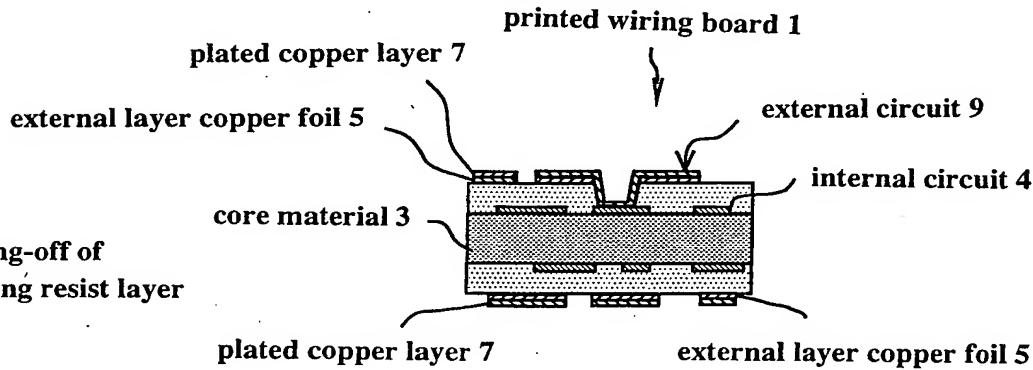


FIG. 4

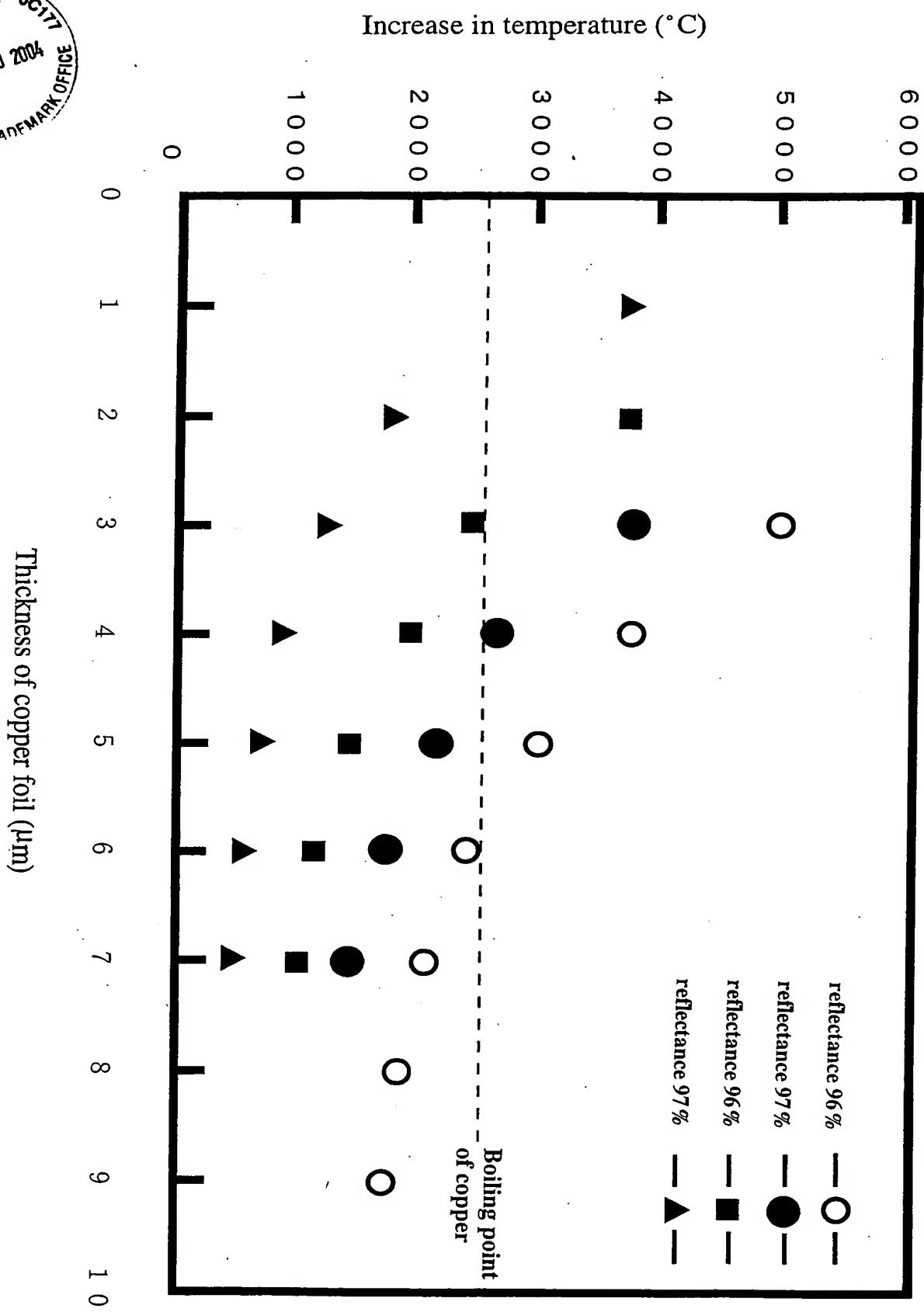
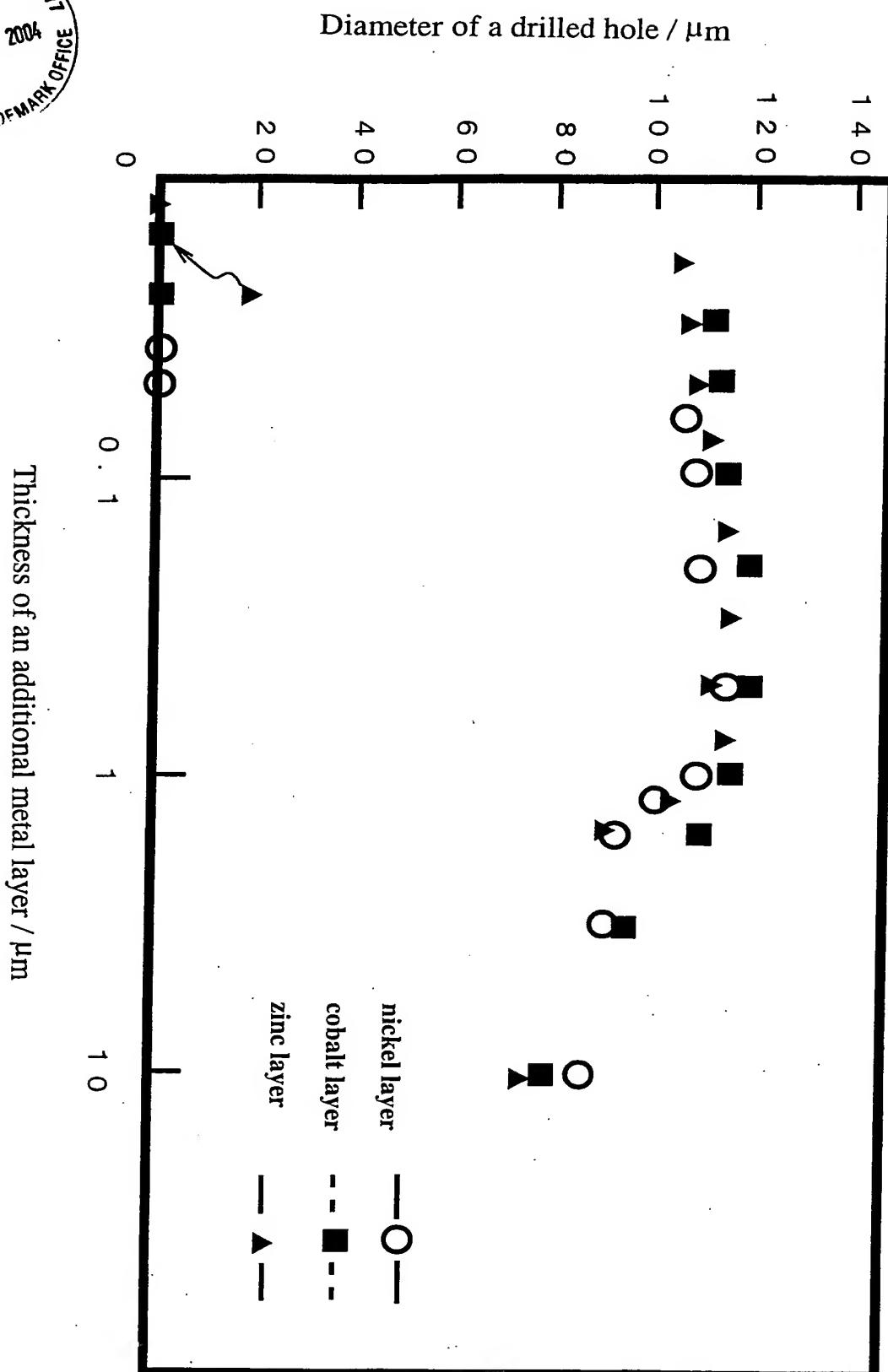


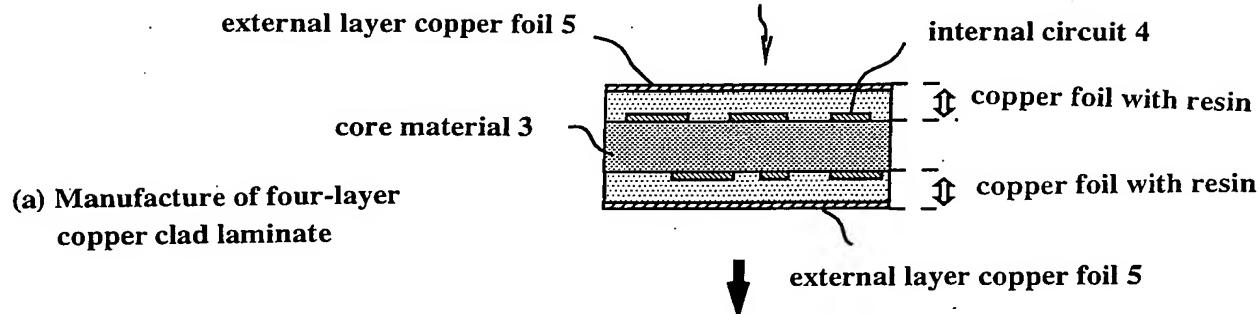
FIG. 5



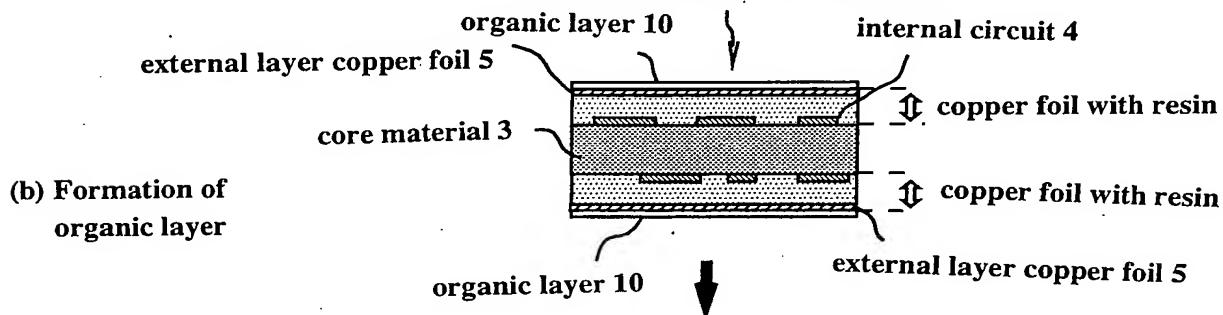
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FIG. 6

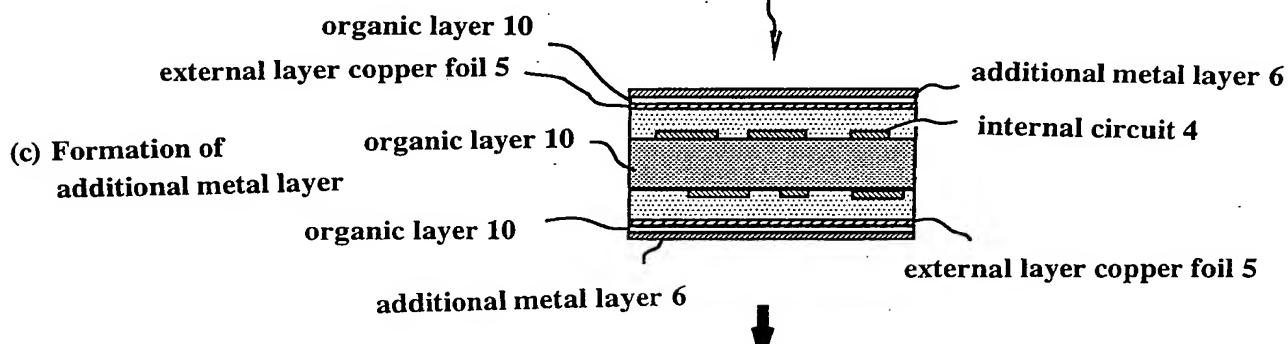
four-layer copper clad laminate 2



four-layer copper clad laminate 2



four-layer copper clad laminate 2



(d) Hole-drilling by laser

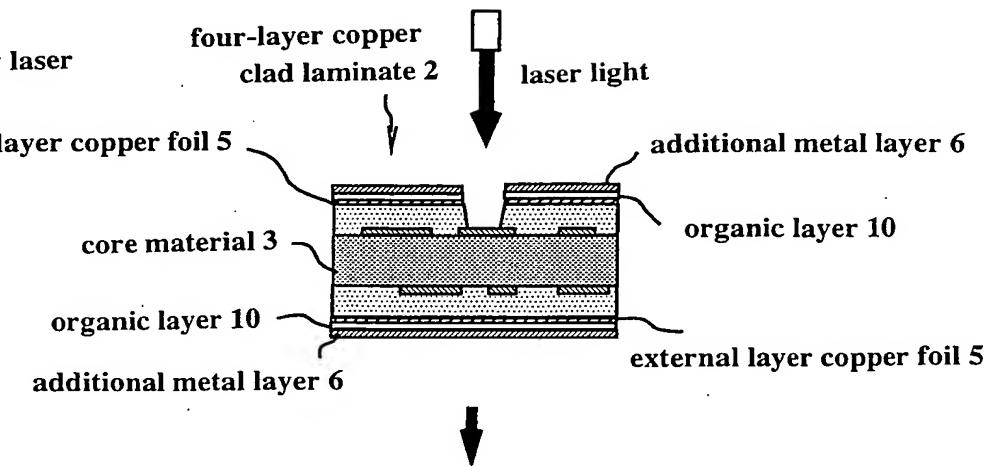
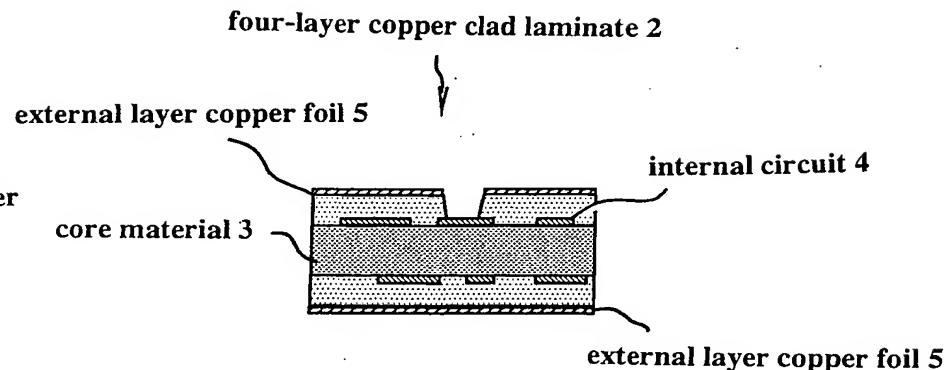


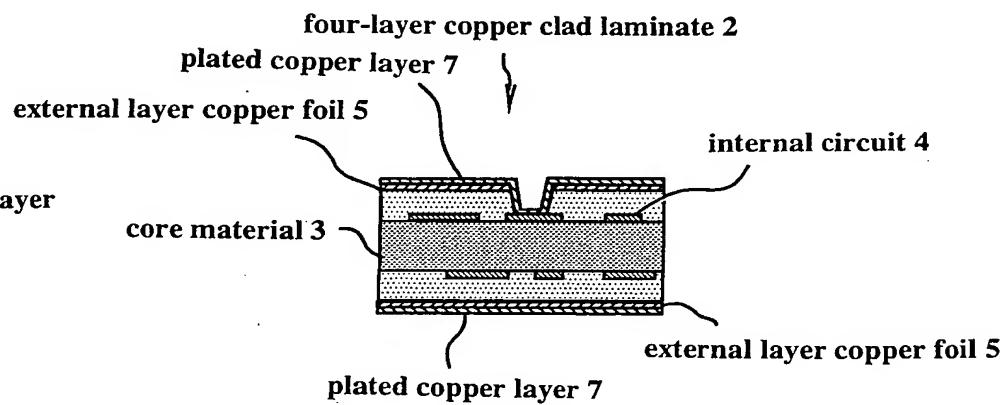
FIG. 7



(e) Peeling-off of
additional metal layer
and organic layer



(f) Formation of
plated copper layer



(g) Formation of
etching resist layer

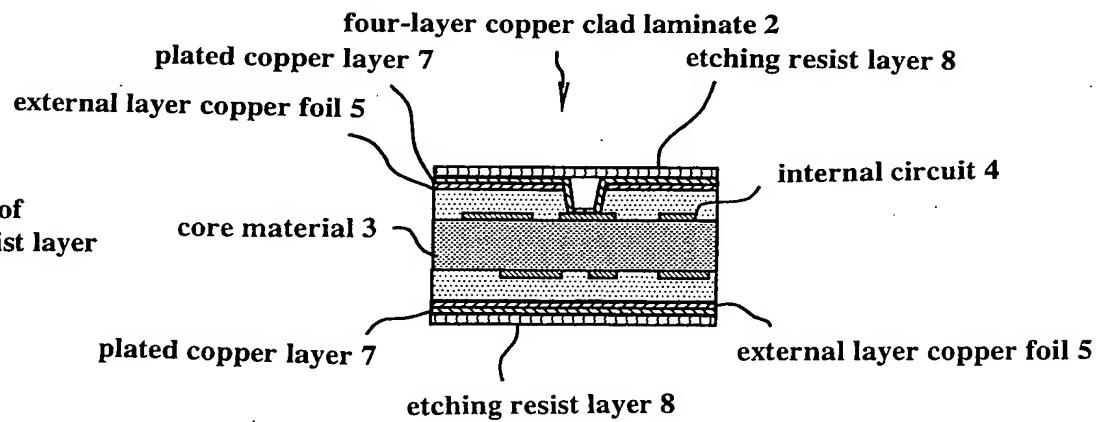
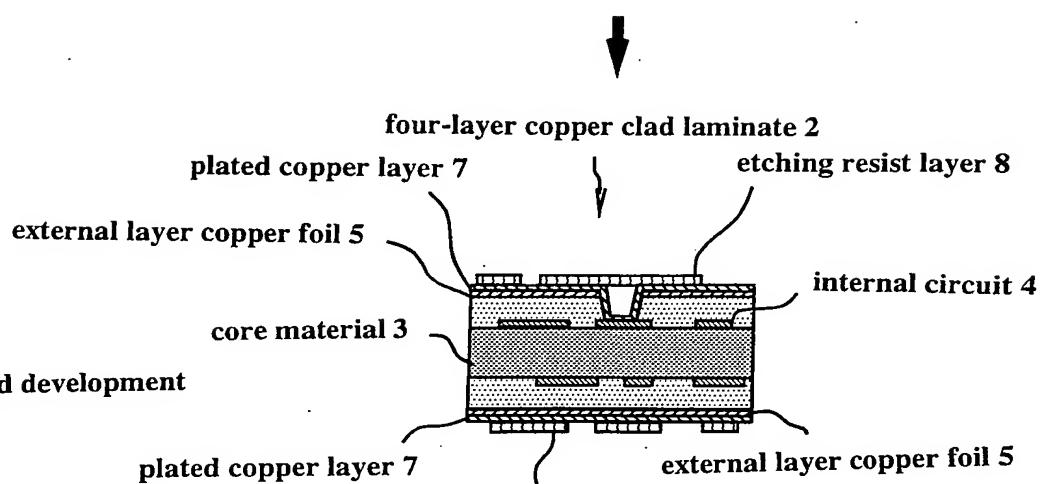


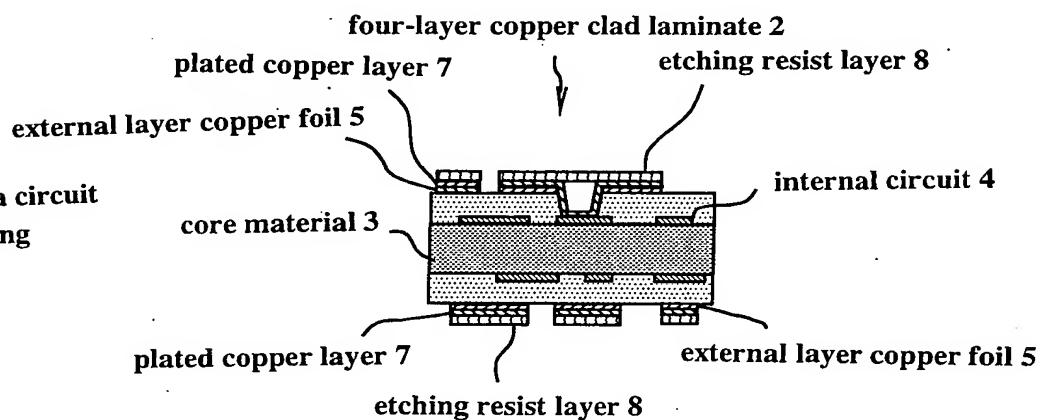
FIG. 8



(h) Exposure and development



(i) Formation of a circuit through etching



(j) Peeling-off of etching resist layer

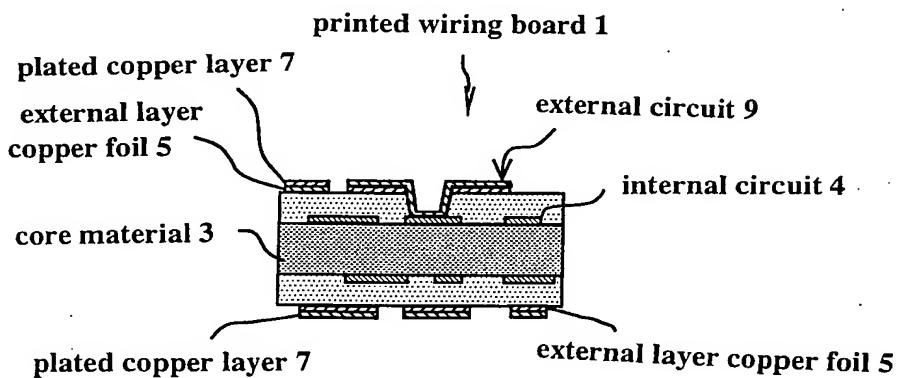


FIG. 9

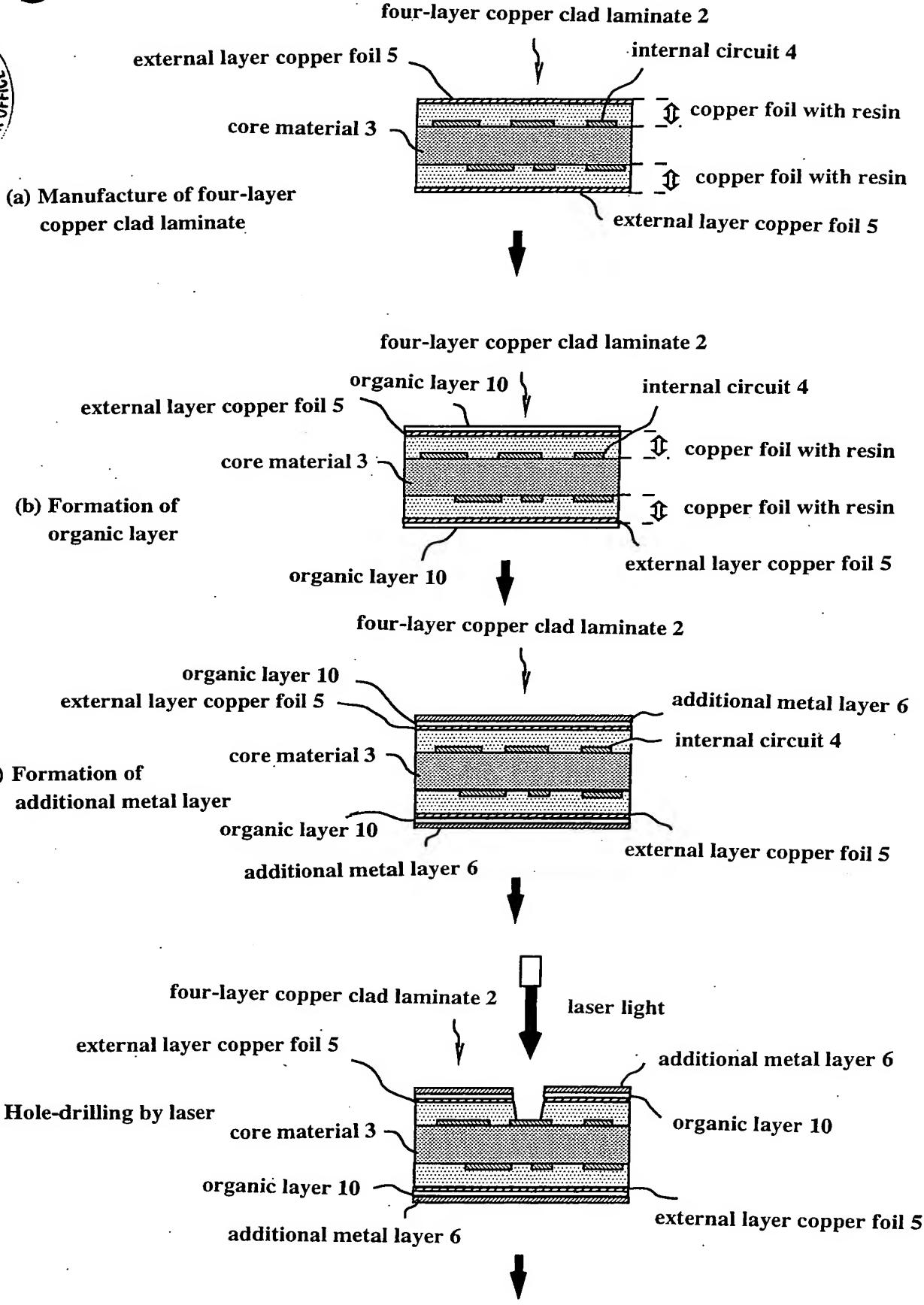


FIG. 10

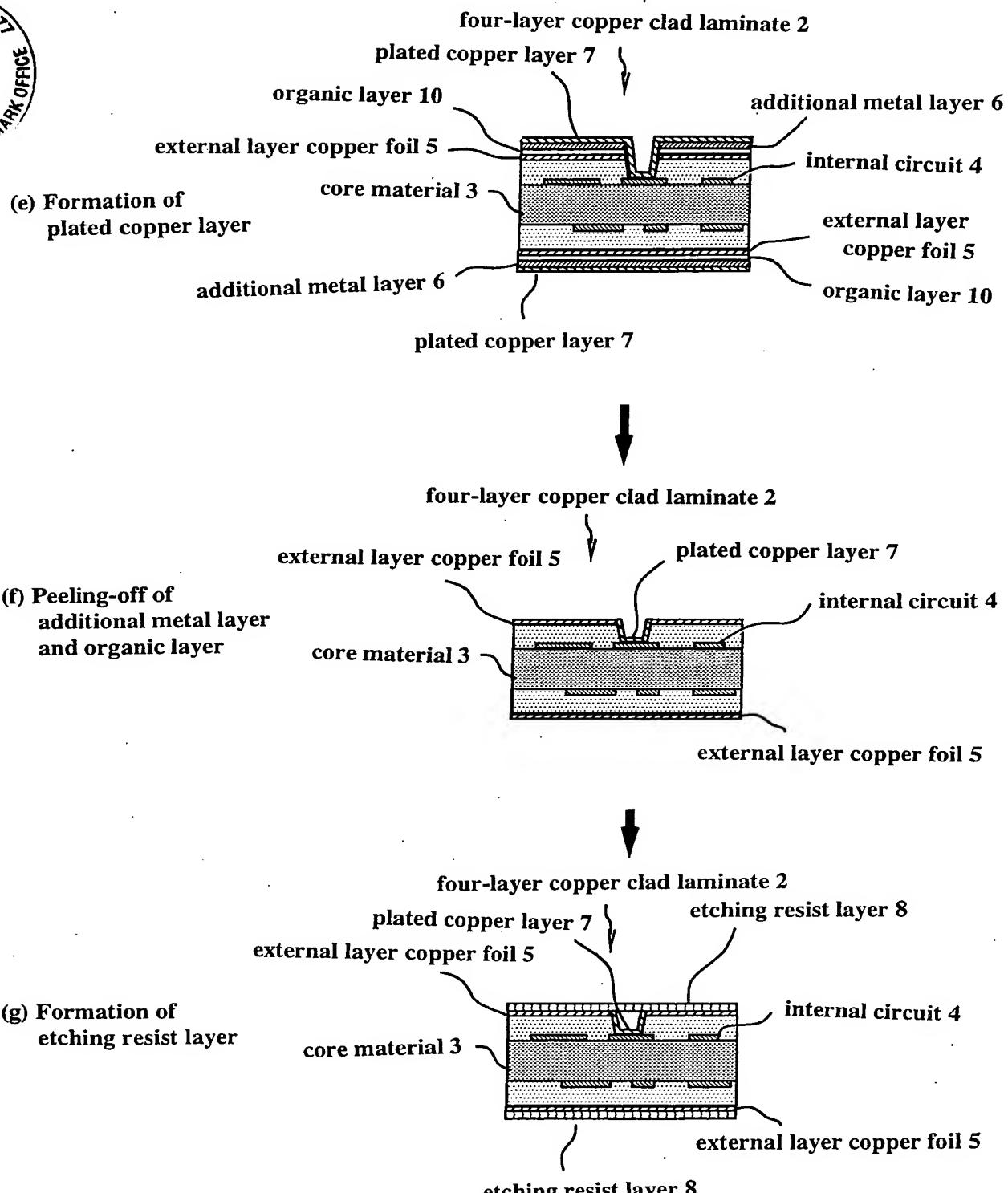


FIG. 11

